L Number	Hits	Search Text	DB	Time stamp
13	2	(("6225192") or ("6020252")).PN.	USPAT; US-PGPUB	2004/05/11 13:49
14	1464746	@ad>19970515 @rlad>19970515	USPAT; US-PGPUB	2004/05/11 13:51
15	82	"smart-cut" and keV	USPAT; US-PGPUB	2004/05/11 13:52
16	0	("smart-cut" and keV) not (@ad>19970515 @rlad>19970515)	USPAT; US-PGPUB	2004/05/11 13:52
17	206	"smart-cut"	USPAT; US-PGPUB	2004/05/11 13:52
18	0	"smart-cut" not (@ad>19970515 @rlad>19970515)	USPAT; US-PGPUB	2004/05/11 13:54
19	2075	hydrogen with (implantation or implant$3)	USPAT; US-PGPUB	2004/05/11 14:46
20	675464	bond$3	USPAT; US-PGPUB	2004/05/11 13:55
21	1267	(hydrogen with (implantation or implant$3)) and bond$3	USPAT; US-PGPUB	2004/05/11 13:55
22	2253397	split$ or splitting or separat$3	USPAT; US-PGPUB	2004/05/11 14:47
23	599815	cleav$3 break$3	USPAT; US-PGPUB	2004/05/11 13:55
24	2431879	(split$ or splitting or separat$3) or (cleav$3 break$3)	USPAT; US-PGPUB	2004/05/11 14:47
27	1073	((hydrogen with (implantation or implant$3)) and bond$3) and ((split$ or splitting or separat$3) or (cleav$3 break$3))	USPAT; US-PGPUB	2004/05/11 13:57
28	193	(((hydrogen with (implantation or implant$3)) and bond$3) and ((split$ or splitting or separat$3) or (cleav$3 break$3))) not (@ad>19970515 @rlad>19970515)	USPAT; US-PGPUB	2004/05/11 13:58
29	551738	semiconductor or ic or "integrated circuit" or microelectronic	USPAT; US-PGPUB	2004/05/11 14:46
30	419932	silicon	USPAT; US-PGPUB	2004/05/11 13:58
31	153	((((hydrogen with (implantation or implant$3)) and bond$3) and ((split$ or splitting or separat$3) or (cleav$3 break$3))) not (@ad>19970515 @rlad>19970515)) and silicon	USPAT; US-PGPUB	2004/05/11 13:58
33	128	(semiconductor or ic or "integrated circuit" or microelectronic) and (((((hydrogen with (implantation or implant$3)) and bond$3) and ((split$ or splitting or separat$3) or (cleav$3 break$3))) not (@ad>19970515 @rlad>19970515)) and silicon)	USPAT; US-PGPUB	2004/05/11 13:59
34	899	hydrogen with (implantation or implant$3)	EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:46
35	1237339	semiconductor or ic or "integrated circuit" or microelectronic	EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:46
37	1805237	split$ or splitting or separat$3 or cleav$3 or break$3	EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:48
38	73	(hydrogen with (implantation or implant$3)) and (semiconductor or ic or "integrated circuit" or microelectronic) and (split$ or splitting or separat$3 or cleav$3 or break$3)	EPO; JPO; DERWENT; IBM_TDB	2004/05/11 14:49
-	65379	438/$.ccls.	USPAT; US-PGPUB	2004/03/31 19:04

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-	25311	keV		USPAT; US-PGPUB	2004/05/10 18:08